XP-002276331

AN - 1989-366552 [25]
A - [001] 014 03- 041 046 047 050 055 056 074 077 081 082 143 155 157 158 371 375 456 461 476 532 537 575 597 602 688
- [002] 014 03- 034 055 056 072 074 076 117 122 28& 371 375 456 461 476 532 537 575 597 602
- [003] 014 03- 034 055 056 072 074 076 27& 371 375 456 461 476 532 537 575 597 602
AP - JP19880000000 19880120
CPY - AROK
DC - A18 A23 A32
FS - CPI
IC - B29C45/16
KS - 0229 0239 0248 0304 0306 0307 0376 0377 0500 0535 1096 1292 2343 2465 2545 2575 2661 3011 3160 3161
MC - A09-D01 A11-B12A
PA - (AROK) ARON KASEI KK
PN - JP1186312 A 19890725 DW198950 004pp
PR - JP19880000000 19880120; JP19880010206 19880120
XA - C1989-162425
XIC - B29C-045/16
AB - J01186312 A thermoplastic resin (A) is injection moulded into the cavity of mould to form a first resin layer, and then thermoplastic resin (B) which is the same resin or a resin having the difference in the solubility parameters. of (A) and (B) = up to 1.0 is injection moulded at a temp. capable of softening and fluidising the first resin (A).
- Pref. resins are e.g. Polystyrene (solubility parameter: SP = 8.8), acrylonitrile butadiene styrene terpolymer (SP = 9.3), acrylonitrile/styrene copolymer (SP = 9.5), PV (SP = 9.5), PMMA-acrylate (SP = 9.3), polyethylene (SP = 7.7), polypropylene (SP = 7.9) or polycarbonate (SP = 9.9) and resin (A) and resin (B) are selected so that the difference in SP = up to 1.0.
- USE/ADVANTAGE - The injection moulding provides a double layered prod. having smooth surface free from sink without increasing the material costs and without extending the moulding cycle.
IW - INJECTION MOULD DOUBLE LAYER PRODUCT FORMING FIRST RESIN LAYER CAVITY MOULD SECOND RESIN TEMPERATURE CAPABLE SOFTEN FIRST LAYER
IKW - INJECTION MOULD DOUBLE LAYER PRODUCT FORMING FIRST RESIN LAYER CAVITY MOULD SECOND RESIN TEMPERATURE CAPABLE SOFTEN FIRST LAYER
NC - 001
OPD - 1988-01-20
ORD - 1989-07-25
PAW - (AROK) ARON KASEI KK
TI - Injection moulding double layer prod. - involves forming first resin layer in cavity then moulding second resin at temp. capable of softening first layer